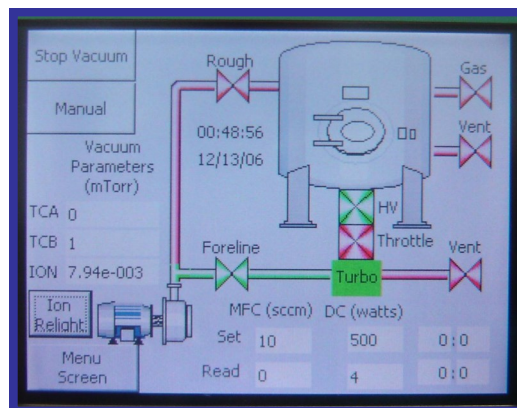


Hummer® BC-16 Series

ONE SYSTEM IN A FAMILY OF PLANAR MAGNETRON SPUTTERING SYSTEMS

THIN FILM DEPOSITION OF METALS AND INSULATORS



TOUCH-PANEL PROCESS CONTROL

Vacuum and Process Control all in one.
Functions are clearly displayed

QUARTZING
CV DOT MATRIX
FAILURE ANALYSIS
MATERIALS RESEARCH
SUPERCONDUCTOR RE-
SEARCH

BC Systems are available in sizes;
16", 20", 24" and 30" D-style chambers
(BC-20 chamber shown in photo)

The **HUMMER BC-16** sputter coater combines a high degree of process control and flexibility with ease of operation.

THIN FILM RESEARCH - FAILURE ANALYSIS - PRODUCTION SUPPORT

HUMMER BC-16

PLANAR MAGNETRON SOURCE

TARGET DIAMETER -
2" Standard,
Optional - 3" & 4" diameter
sources and Multiple sources
TARGET THICKNESS - 1/16 to
1/4" standard
TARGET MATERIALS - Metals
and / or insulators
SOURCE MOUNTING - Quick
coupling to chamber, shutters,
shields between sources as
necessary
POWER SUPPLY - 300 watts,
13.56 MHz. Standard
Optional - 600, 1000 watts RF
at 13.56 MHz.
1500 Watts Standard, Optional
- 2500 Watts DC, or various
combinations of supplies
COOLING WATER - .2 to 10
GPM required.
Optional - Recirculation system
TARGET MOUNTING - Mechanical
clamp or magnetic keeper
depending upon requirement

STAGE FIXTURE

SIZE - 2", 3", 4", 6", 8" or 12"
MOTION -360° rotation standard.
Optional - Variable angle of inci-
dence to sputter source
COOLING - Optional
REVERSE SPUTTER/ETCH - Optional
HEATED - Optional to 1000° Celsius

SOURCE OPTIONS

Anatech USA offers alternatives for source configuration.
Contact our sales staff.

OVERALL SYSTEM

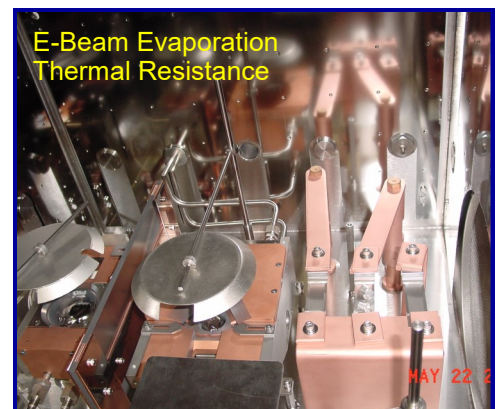
CHAMBER - 304 Stainless steel,
16" ID nominal, aluminum door,
4" Door view port, roughing,
High Vac pump and instrument
ports
CONTROL - Siemens S7-200
Series PLC control for each vacu-
um function and sputtering
source. Fully integrated with easy
"Touch-Panel" control pad for
diagnostic and setting system pa-
rameters
DESIGN - Floor mount cabinet
on casters with leveling pads
SAFETY INTERLOCKS - Water, door
and vacuum interlocks.
ELECTRICAL REQUIREMENTS -
40-75 AMP, 208-240 Volt,
50/60 HZ
SPUTTERING - Standard top down
sputtering. Optional - Sputter-up
or horizontal sputter
AUTOMATIC SEQUENCING -
Standard

IONIZATION SPECIES

GAS REQUIREMENTS - Argon
regulated from 5 to 20 PSI
OPERATING PRESSURE -
 2×10^{-3} to 5×10^{-2}
REACTIVE SPECIES - Optional

VACUUM SYSTEM

PUMPING - Roughing pump and Tur-
bo molecular pump - Standard
Optional - Cryo pump or Larger
pumps
VACUUM GAUGING - Convectron
gauges (2), Ion gauge (1).
Atmosphere to 1×10^{-8} TORR
VALVES - Electro-Pneumatic actuated
High Vacuum/Throttle valve be-
tween pump and chamber. Fore-line
and chamber roughing isolation
valves. Pneumatic air or nitrogen
(clean, dry) operating at 60-PSI.
GAS CONTROL - Mass Flow Controller
(1) 100 sccm. Optional - Gases (3)
maximum, for mixing and reactive
gas sputtering



CALL ANATECH USA TODAY TO DISCUSS YOUR APPLICATION

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